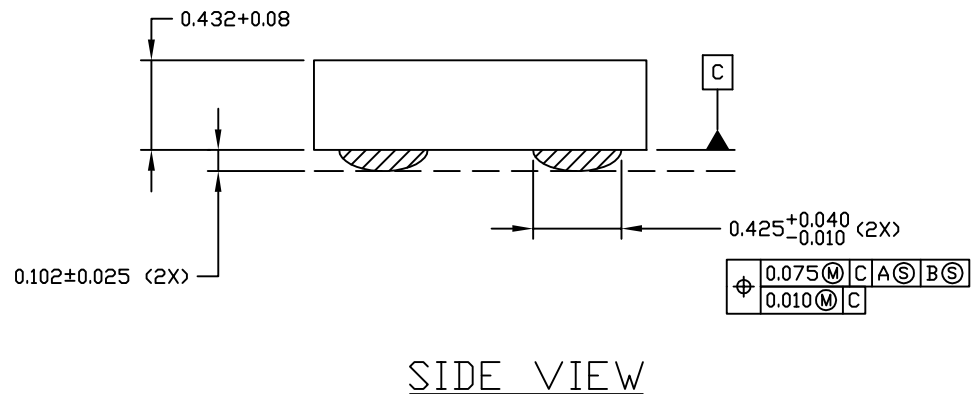


SOLDER PASTE APERTURE
0.43X0.68 [0.017X0.027]

TOP VIEW

RECOMMENDED
SUBSTRATE LAND PATTERN



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. LASER MARK
4. LANDING PAD NOT DEFINED BY SOLDER MASK
5. ALL DIMENSIONS APPLY TO LEADED (-), PKG. CODES ONLY.
6. PACKAGE CODE: BF211-2

MAXIM

TITLE:
PACKAGE OUTLINE, 2 BUMPS FLIP CHIP,
0.91x1.60x0.432mm, 0.933mm PITCH

APPROVAL	DOCUMENT CONTROL NO. 21-0379	REV. B	1/1
----------	---------------------------------	-----------	-----

-DRAWING NOT TO SCALE-